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From the Director's Desk
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Manufacturing Standards for Flexible and Hybrid Electronics

As previously discussed in this space, recent advances in advanced printing and packaging technologies have led to the creation of new breed of products, which can integrate multiple silicon circuits and sensors onto a flexible substrate. [Read More](#)

Report on Activities of SEMI Live Gas Study Group

CVD (Chemical Vapor Deposition) and dry etching for the manufacturing process of semiconductors and FPD use a wide range of gases for reactions. [Read More](#)

Flexible Hybrid Electronics: Survey Results on Technology Manufacturing and Standards Needs

FlexTech, SEMI, and IPC, conducted an industry survey during November and December, 2015, to understand technology, manufacturing and standards needs for flexible & hybrid electronics. [Read More](#)

Taiwan I&C Committee Chapter/ Backend Factory Integration Task Force Update

The Taiwan Information and Control (I&C) Committee was held on Sep 3rd, 2015 in conjunction with SEMICON Taiwan to approve 3 TFOFs to formally start the operation of 3 task forces. [Read More](#)

February 12, 2016 Edition of the Procedure Manual Now Available

In early Feb 2016, the International Standards Committee (ISC) Regulations Subcommittee approved changes to the SEMI Procedural Manual (PM). [Read More](#)

Korea HB-LED Update

Korea HB-LED Chapter Formation Group, CFG, recently received approval for the 5 SNARFs. [Read More](#)

S2 Update

At the last EHS NA TC Chapter meeting held in November 2015, two critical delay revision ballots for SEMI S2-0715a, Environmental, Health, and Safety Guideline for Semiconductor Manufacturing Equipment were approved. [Read More](#)

Standards Calendar

April 4-7: [North America Standards Spring 2016 Meetings](#)

[Click here for all Standards events.](#)

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